

### AMENDED MATERIAL

The abstract has been amended as follows:

[The present invention provides an] An interconnect formed between layers of a circuit board[, A conductive object is embedded in the layer of a circuit board], wherein a conductive element is embedded in an opening within a laminate of the circuit board, and wherein the conductive element forms at least one contact pad extending beyond a surface of the laminate.

The claims have been amended as follows:

21. (Twice Amended) A method of forming a conductive path within a laminate, comprising:

providing an opening in [a] the laminate; and

pressing a conductive element into the opening wherein a portion of the conductive element forms at least one contact pad extending beyond a surface of the laminate, and wherein the conductive element includes an inner element covered by an outer element.

27. (Twice Amended) A structure for interconnection between circuit layers, comprising:

a conductive element embedded into a laminate wherein a portion of the conductive element forms at least one contact pad extending beyond a surface of the laminate, and wherein the conductive element includes an inner element covered by an outer element.